

<b>PCN Number:</b>	20240520011.0	<b>PCN Date:</b>	May 24, 2024
<b>Title:</b>	Datasheet for TMS320F28002x		
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services
<b>Change Type:</b>	Electrical Specification		

## PCN Details

### Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**TMS320F280025, TMS320F280025-Q1**  
**TMS320F280025C, TMS320F280025C-Q1, TMS320F280023, TMS320F280023-Q1**  
**TMS320F280023C, TMS320F280021, TMS320F280021-Q1**  
SPRSP45C – MARCH 2020 – REVISED APRIL 2024

### Changes from December 18, 2020 to April 4, 2024 (from Revision B (December 2020) to Revision C (April 2024))

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• <i>Features</i> section: Changed "On-chip crystal oscillator or external clock input" to "Crystal oscillator or external clock input". Changed the number of individually programmable multiplexed General-Purpose Input/Output (GPIO) pins from 39 to 43.....	1
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The datasheet number will be changing.

Device Family	Change From:	Change To:
TMS320F28002x	SPRSP45B	<b>SPRSP45C</b>

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMS320F280025>

#### Reason for Change:

To accurately reflect device characteristics.

<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device			
<b>Changes to product identification resulting from this PCN:</b>			
None.			
<b>Product Affected:</b>			
F280021PTSR	F280025CPMS	F280023CPNSR	F280025PNQR
F280023CPMSR	F280025CPMSR	F280025PMSR	F280025PTQR
F280025PTS	F280023PTQR	F280025PNSR	F280025CPNSR
F280023PMSR	F280023CPTSR	F280025CPTQR	F280025CPNQR
F280023PTSR	SM288888PMSR	F280021PTQR	F280023PNQR
F280025PNS	F280025CPTSR	F280023PNSR	F280025PMS
F280025PTSR	F280023PMQR	F280025PMQR	F280025CPMQR

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